

# TC-8001G

Polycarbonate compound resin

## General Information

### Description

Thermal conductive, 20% graphite filled  
Medium viscosity, easy mold release  
Available in opaque color only

### Applications

Heat sinks, cooling units, electric/electronic housings, etc.

## Typical properties<sup>1</sup>

	Test Method	Typical value	Unit
<b>Physical</b>			
Melt Flow Index, 300 °C, 1.2 kg	ASTM D1238	9	g/10min
Specific Gravity	ASTM D792	1.28	
Mold Shrinkage	HPC method	0.4 ~ 0.6	%
<b>Mechanical</b>			
Tensile Strength, yield, 50 mm/min	ASTM D638	470	kg <sub>f</sub> /cm <sup>2</sup>
Tensile Elongation, break, 50 mm/min	ASTM D638	-	%
Flexural Strength, yield, 10 mm/min	ASTM D790	670	kg <sub>f</sub> /cm <sup>2</sup>
Flexural Modulus, 10 mm/min	ASTM D790	54,000	kg <sub>f</sub> /cm <sup>2</sup>
IZOD Impact Strength, notched, 23 °C, 1/8"	ASTM D256	6	kg <sub>f</sub> ·cm/cm
	ASTM D256	-	kg <sub>f</sub> ·cm/cm
<b>Thermal</b>			
Thermal conductivity	Hot-wire method	0.7	W/m·K
Heat Distortion Temp. 4.6 kg <sub>f</sub> /cm <sup>2</sup>	ASTM D648	-	°C
	ASTM D648	140	°C
Vicat Softening Temp. Rate B/50	ASTM D1525	-	°C

## Notes

ISO 9001, 14001, /TS 16949

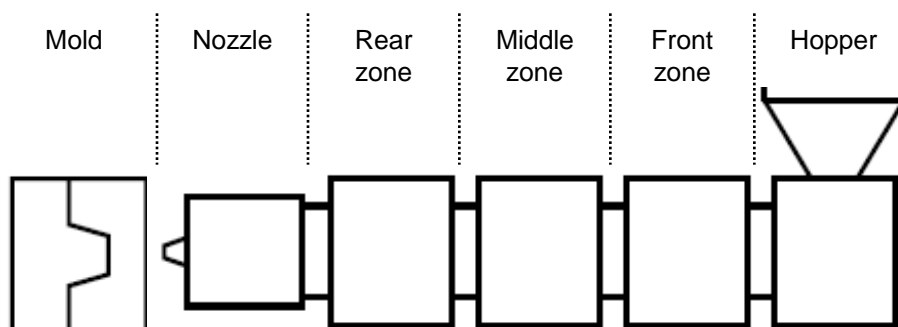
<sup>1</sup> Typical properties : these are not to be construed as specifications.

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## Processing guides<sup>1</sup>

	Typical value	Unit	
<b>Drying condition</b>			
Drying temperature	120	°C	
Drying time	4	hr	
Maximum moisture content	0.02	%	
<b>Injection molding</b>			
Melt temperature	290 ~ 310	°C	
Nozzle temperature	280 ~ 300	°C	
Barrel	Rear zone	290 ~ 310	°C
	Middle zone	280 ~ 300	°C
	Front zone	270 ~ 290	°C
Hopper temperature	60 ~ 80	°C	
Mold temperature	60 ~ 90	°C	



## Recycling

Sprues and runners can be reground with virgin resin within the ratio of 20%. Care must be taken to ensure that the regrind is free from impurities and regrind should not be used in applications where impact performance and/or agency compliance are required.

## Notes

ISO 9001, 14001, /TS 16949

<sup>1</sup> Processing guides : Typical processing parameters are noted. Actual processing conditions will depend on machine size, mold design, material residence time, shot size, etc.